ABSTRACT

The present invention alleviates the operational problems in production of flip chips and provides a semiconductor device superior in various reliabilities. The preset invention lies in an encapsulated semiconductor device comprising:

a polybenzoxazole resin film for chip protection, obtained by coating, on a circuit-formed chip, a positive photosensitive resin composition comprising 100 parts by weight of a polyamide and 1 to 100 parts by weight of a photosensitive diazoquinone compound, and subjecting the coated composition to patterning and curing, and

(b) a bump electrode.